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APPLICATION NO.	FII	LING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.	
10/708,203	0	02/16/2004	SHIH-CHANG SHEI	11114-US-PA	2202	
31561	7590	10/05/2004		EXAMINER		
JIANQ CH	YUN INT	TELLECTUAL PR	QUINTO, KEVIN V			
7 FLOOR-1,				ART UNIT	PAPER NUMBER	
ROOSEVEL		SECTION 2		ARTORIT	TATER NUMBER	
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Please find below and/or attached an Office communication concerning this application or proceeding.

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		Application No.	Applicant(s)	
		10/708,203	SHEI ET AL.	
	Office Action Summary	Examiner	Art Unit	
		Kevin Quinto	2826	
Period f	The MAILING DATE of this communication or Reply	appears on the cover sheet wi	th the correspondence address	
THE - Extended - If th - If No - Fail Any	HORTENED STATUTORY PERIOD FOR RE MAILING DATE OF THIS COMMUNICATIO ensions of time may be available under the provisions of 37 CFF or SIX (6) MONTHS from the mailing date of this communication. The period for reply specified above is less than thirty (30) days, a operiod for reply is specified above, the maximum statutory per ure to reply within the set or extended period for reply will, by state of the period for reply will, by state or extended period for reply will according to the period for reply will be p	N. R 1.136(a). In no event, however, may a r . reply within the statutory minimum of thin riod will apply and will expire SIX (6) MON atute, cause the application to become AB	eply be timely filed y (30) days will be considered timely. THS from the mailing date of this communication. ANDONED (35 U.S.C. § 133).	
Status				
1)[🗆	Responsive to communication(s) filed on 0	7 July 2004.		
· · · · ·		This action is non-final.		
3)	Since this application is in condition for allo closed in accordance with the practice under			
Disposit	tion of Claims			
5)⊠ 6)⊠ 7)⊠	Claim(s) <u>1-26</u> is/are pending in the applicat 4a) Of the above claim(s) is/are with Claim(s) <u>9-18 and 21-26</u> is/are allowed. Claim(s) <u>1,3-8 and 19</u> is/are rejected. Claim(s) <u>2 and 20</u> is/are objected to. Claim(s) are subject to restriction and	drawn from consideration.		
Applicat	tion Papers			
10)	The specification is objected to by the Example The drawing(s) filed on is/are: a) and a Applicant may not request that any objection to the Replacement drawing sheet(s) including the continuous that or declaration is objected to by the	accepted or b) objected to the drawing(s) be held in abeyand rection is required if the drawing(ce. See 37 CFR 1.85(a). s) is objected to. See 37 CFR 1.121(d).	
Priority	under 35 U.S.C. § 119			
а)	Acknowledgment is made of a claim for fore All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the papplication from the International Bur See the attached detailed Office action for a light	ents have been received. ents have been received in A priority documents have been reau (PCT Rule 17.2(a)).	oplication No received in this National Stage	
	at(s) ce of References Cited (PTO-892) ce of Draftsperson's Patent Drawing Review (PTO-948)		ummary (PTO-413) /Mail Date	
3) 🔲 Infor	ce of Draftsperson's Patent Drawing Review (PTO-948) mation Disclosure Statement(s) (PTO-1449 or PTO/SB/ er No(s)/Mail Date		formal Patent Application (PTO-152)	

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DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1, 3-8, and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Slater, Jr. et al. (USPN 6,791,119 B2) in view of Nitta et al. (United States Patent Application Publication No. US 2002/0163302 A1) and further in view of Oku et al. (USPN 6,497,944 B1).
- 3. In reference to claim 1, Slater, Jr. et al. (USPN 6,791,119 B2, hereinafter referred to as the "Slater" reference) discloses a similar device. Figure 4 of Slater illustrates a light emitting diode (LED) with a device substrate (110) and a first doped layer (120) formed on it. There is a light emitting layer (130) formed on the first doped layer (120). There is a second doped layer (140) formed on the light emitting layer (130). The first doped layer (120) is n-type while the second doped layer (140) is p-type; the two layers are both formed of a III-V semiconductor material. There is a transparent conductive oxide layer (412) on the second doped layer (150). There is a reflecting layer (414) on the transparent conductive oxide layer (412). There is an electrode (155) formed on the reflecting layer (414) and another electrode (160) formed on the first doped

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layer (120). Slater does not disclose the use of a superlattice contact layer, however the use of such a layer is well known in the art. Nitta et al. (United States Patent Application Publication No. US 2002/0163302 A1, hereinafter referred to as the "Nitta" reference) discloses the use of a superlattice contact layer (126, figure 2) in order to decrease contact resistance (p.5, paragraph 75). Oku et al. (USPN 6,497,944 B1, hereinafter referred to as the "Oku" reference) discloses that lowering the contact resistance leads to a reduction in operating voltage which is a desired quality in light emitting devices (column 2, lines 19-25). In view of Nitta and Oku, it would therefore be obvious to use a superlattice contact layer in the device of Slater.

- 4. With regard to claim 3, Nitta discloses the use of a III-V p-type semiconductor multi-layer structure (p.5, paragraph 75).
- 5. In reference to claim 4, Slater discloses the use of gallium nitride as the semiconductor material (column 7, lines 36-41).
- 6. With regard to claim 5, Slater discloses the use of a quantum-well light emitting layer (column 7, lines 53-57).
- 7. In reference to claim 6, Slater meets the limitation of the claim (column 11, lines 30-34).
- 8. With regard to claim 7, the first doped layer (120) is n-type while the second doped layer (140) is p-type.
- 9. In reference to claim 8, Slater meets the limitation of the claim (column 7, lines 1-3).

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10. In reference to claim 19, Slater (USPN 6,791,119 B2) discloses a similar device. Figure 4 of Slater illustrates a flip-chip light emitting diode (LED) with a package substrate (210). The LED device is face down and flipped on the package substrate. The LED device has a device substrate (110) and a first doped layer (120) formed on it. There is a light emitting layer (130) formed on the first doped layer (120). There is a second doped layer (140) formed on the light emitting layer (130). The first doped layer (120) is n-type while the second doped layer (140) is p-type; the two layers are both formed of a III-V semiconductor material. There is a transparent conductive oxide layer (412) on the second doped layer (140). There is a reflecting layer (414) on the transparent conductive oxide layer (412). There is an electrode (155) formed on the reflecting layer (414) and another electrode (160) formed on the first doped layer (120). Slater does not disclose the use of a superlattice contact layer. however the use of such a layer is well known in the art. Nitta (United States Patent Application Publication No. US 2002/0163302 A1) discloses the use of a superlattice contact layer (126, figure 2) in order to decrease contact resistance (p.5, paragraph 75). Oku (USPN 6,497,944 B1) discloses that lowering the contact resistance leads to a reduction in operating voltage which is a desired quality in light emitting devices (column 2, lines 19-25). In view of Nitta and Oku. it would therefore be obvious to use a superlattice contact layer in the device of Slater.

11. Claims 1, 3-7, and 19 are rejected under 35 U.S.C. 103(a) as being unpatentable over Tamura et al. (United States Patent Application Publication

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No. US 2004/0113156 A1) in view of Nitta et al. (United States Patent Application Publication No. US 2002/0163302 A1) and further in view of Oku et al. (USPN 6,497,944 B1).

12. In reference to claim 1, Tamura et al. (United States Patent Application Publication No. US 2004/0113156 A1, hereinafter referred to as the "Tamura" reference) discloses a similar device. Figure 4 of Tamura illustrates a light emitting diode (LED) with a device substrate (11) and a first doped layer (12) formed on it. There is a light emitting layer (13) formed on the first doped layer (12). There is a second doped layer (14) formed on the light emitting layer (13). The first doped layer (12) is n-type while the second doped layer (14) is p-type; the two layers are both formed of a III-V semiconductor material (p.4, paragraph 56). Tamura discloses (p.4, paragraphs 58-59) that there is a transparent conductive oxide layer (15) on the second doped layer (14). There is a reflecting layer (21) on the transparent conductive oxide layer (15). There is an electrode (22) formed on the reflecting layer (414) and another electrode (17) formed on the first doped layer (12). Tamura does not disclose the use of a superlattice contact layer, however the use of such a layer is well known in the art. Nitta (United States Patent Application Publication No. US 2002/0163302 A1) discloses the use of a superlattice contact layer (126, figure 2) in order to decrease contact resistance (p.5, paragraph 75). Oku (USPN 6,497,944 B1) discloses that lowering the contact resistance leads to a reduction in operating voltage which is a desired quality in light emitting devices (column 2, lines 19-25).

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In view of Nitta and Oku, it would therefore be obvious to use a superlattice contact layer in the device of Tamura.

- 13. With regard to claim 3, Nitta discloses the use of a III-V p-type semiconductor multi-layer structure (p.5, paragraph 75).
- 14. In reference to claim 4, Tamura discloses the use of gallium nitride as the semiconductor material (p.4, paragraph 56).
- 15. With regard to claim 5, Tamura discloses the use of a quantum-well light emitting layer (p.4, paragraph 56).
- 16. In reference to claim 6, Tamura meets the limitation of the claim (p.4, paragraphs 58-59).
- 17. With regard to claim 7, the first doped layer (12) is n-type while the second doped layer (14) is p-type (p.4, paragraph 56).
- 18. In reference to claim 19, Tamura (USPN 6,791,119) discloses a similar device. Figure 4 of Tamura illustrates a flip-chip light emitting diode (LED) with a package substrate (20). The LED device is face down and flipped on the package substrate. The LED device has a device substrate (11) and a first doped layer (12) formed on it. There is a light emitting layer (13) formed on the first doped layer (12). There is a second doped layer (14) formed on the light emitting layer (13). The first doped layer (12) is n-type while the second doped layer (14) is p-type; the two layers are both formed of a III-V semiconductor material (p.4, paragraph 56). Tamura discloses (p.4, paragraphs 58-59) that there is a transparent conductive oxide layer (15) on the second doped layer (14). There is a reflecting layer (21) on the transparent conductive oxide layer

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(15). There is an electrode (22) formed on the reflecting layer (21) and another electrode (17) formed on the first doped layer (12). Tamura does not disclose the use of a superlattice contact layer, however the use of such a layer is well known in the art. Nitta (United States Patent Application Publication No. US 2002/0163302 A1) discloses the use of a superlattice contact layer (126, figure 2) in order to decrease contact resistance (p.5, paragraph 75). Oku (USPN 6,497,944 B1) discloses that lowering the contact resistance leads to a reduction in operating voltage which is a desired quality in light emitting devices (column 2, lines 19-25). In view of Nitta and Oku, it would therefore be obvious to use a superlattice contact layer in the device of Tamura.

Allowable Subject Matter

- 19. Claims 9-18 and 21-26 are allowed.
- 20. Claims 2 and 20 are objected to as being dependent upon a rejected base claim, but would be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims.
- 21. The following is a statement of reasons for the indication of allowable subject matter: the examiner is unaware of any prior art which suggests or renders obvious a flip-chip light emitting diode (LED) package with a package substrate and an LED (which is face down and inverted on the package substrate) that has the following layer structure: device substrate, a first doped layer made of a III-V semiconductor material of a first conductivity type (having an electrode), a light emitting layer, a second doped layer made of a III-V

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semiconductor material of a second conductivity type, a strained superlattice contact layer, a transparent conductive oxide layer, a transparent insulating layer, and a reflecting layer (having an electrode).

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Kevin Quinto whose telephone number is (571) 272-1920. The examiner can normally be reached on M-F 8AM-5PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nathan Flynn can be reached on (571) 272-1915. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

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